

Help

L6

Interrupt

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### Search Results -

Terms

Documents

I10 and (embed\$4 or bury or buried or buries)

8

US Patents Full-Text Database

JPO Abstracts Database

EPO Abstracts Database

Dowload World Patents Index

Database: IBM Technical Disclosure Bulletins

110 and (embed\$4 or bury or buried or  
buries)

Clear

### Search History

Today's Date: 2/6/2001

<u>DB Name</u>	<u>Query</u>	<u>Hit Count</u>	<u>Set Name</u>
JPAB,EPAB,DWPI	I10 and (embed\$4 or bury or buried or buries)	8	<u>L12</u>
JPAB,EPAB,DWPI	I10 and (cure\$1 and curing)	45	<u>L11</u>
JPAB,EPAB,DWPI	filler same resin same component and (circuit or module)	360	<u>L10</u>
JPAB,EPAB,DWPI	filler and resin and component	12625	<u>L9</u>
JPAB,EPAB,DWPI	I7 and filler and resin and component	12	<u>L8</u>
JPAB,EPAB,DWPI	nakatani	9382	<u>L7</u>
JPAB,EPAB,DWPI	09321178	2	<u>L6</u>
JPAB,EPAB,DWPI	05283608	2	<u>L5</u>
JPAB,EPAB,DWPI	5283608	2	<u>L4</u>
JPAB,EPAB,DWPI	689242	4	<u>L3</u>
JPAB,EPAB,DWPI	2138205	5	<u>L2</u>
JPAB,EPAB,DWPI	2138205	5	<u>L1</u>

	Hits	Search Text	DBs
1	1	6038133.pn.	USPAT
2	17	4299873.PN. OR 4417297.PN. OR 4800459.PN. OR 5045381.PN. OR 5153987.PN. OR 5324687.PN. OR 5401688.PN. OR 5401913.PN. OR 5412538.PN. OR 5481795.PN. OR 5484647.PN. OR 5651179.PN. OR 5652042.PN. OR 5677045.PN. OR 5806177.PN. OR 5888627.PN. OR 5939782.PN.	USPAT
3	0	6038133.URPN.	USPAT
4	0	6038133.URPN.	USPAT
5	5630	156/230,233,235,247,249,289,298,299,30 3.1,307.1,307.7.ccls.	USPAT
6	1287173	component or chip	USPAT
7	351679	thermoset or resin	USPAT
8	776860	circuit or wiring	USPAT
9	319	156/230,233,235,247,249,289,298,299,30 3.1,307.1,307.7.ccls. and (component or chip) and (thermoset or resin) and (circuit or wiring)	USPAT
10	228192	bury or buried or buries or embed\$3 or encapsulat\$3	USPAT
11	129	(component or chip) same (bury or buried or buries or embed\$3 or encapsulat\$3) and 156/230,233,235,247,249,289,298,299,30 3.1,307.1,307.7.ccls.	USPAT
12	89	((component or chip) same (bury or buried or buries or embed\$3 or encapsulat\$3) and 156/230,233,235,247,249,289,298,299,30 3.1,307.1,307.7.ccls.) not (156/230,233,235,247,249,289,298,299,30 3.1,307.1,307.7.ccls. and (component or chip) and (thermoset or resin) and (circuit or wiring))	USPAT
13	123	156/230,233,235,247,249,289,298,299,30 3.1,307.1,307.7.ccls. and (thermoset or resin) and (circuit or wiring) and (bury or buried or buries or embed\$3 or encapsulat\$3)	USPAT

	Hits	Search Text	DBs
14	21	(156/230,233,235,247,249,289,298,299,303.1,307.1,307.7.ccls. and (thermoset or resin) and (circuit or wiring) and (bury or buried or buries or embed\$3 or encapsulat\$3)) not (156/230,233,235,247,249,289,298,299,303.1,307.1,307.7.ccls. and (component or chip) and (thermoset or resin) and (circuit or wiring))	USPAT

	L #	Hits	Search Text	DBs	Time Stamp
1	L1	5630	156/230,233,235,247,249,289 ,298,299,303.1,307.1,307.7. ccls.	USPAT	2001/02/06 13:32
2	L2	22	1 and (bury or buried or buries or embed\$3 or encapsulat\$3) same module	USPAT	2001/02/06 13:58
3	L3	1	6143116.pn.	USPAT	2001/02/06 13:44
4	L4	12	2692190.PN. OR 2969300.PN. OR 4751126.PN. OR 4869767.PN. OR 4889584.PN. OR 4912020.PN. OR 5309629.PN. OR 5744758.PN. OR 5746868.PN. OR 5817404.PN. OR 5848466.PN. OR 5925930.PN.	USPAT	2001/02/06 13:44
5	L5	1766	(bury or buried or buries or embed\$4 or encapsulat\$3) same (component or chip) same module	USPAT	2001/02/06 14:00
6	L6	92	5 and (thermoset\$4 or resin) and filler	USPAT	2001/02/06 14:13
7	L7	450	5 and (thermoset\$4 or resin)	USPAT	2001/02/06 14:14
8	L8	448	7 and (circuit or wiring or via or through ad hole)	USPAT	2001/02/06 14:15
9.	L9	356	8 not 6	USPAT	2001/02/06 14:16